

ForTii® TX1 PPA-GF30 FR(40)

30% Glass Fiber Reinforced, PA4T, Electro-friendly, Halogen free and free of red phosphorous, Certified V-0 at 0.35mm

Print Date: 2025-11-04

For Tii® TX1 has robust mechanical & JEDEC Level 2 performance, enabling SMT process without deformation and low risk on blistering. TX1 has stable processing behavior and is suitable for typical consumer electronics connector manufacturing such as I/O, FPC and WTB connectors.

PROPERTIES	TYPICAL DATA	UNIT	TEST METHOD
RHEOLOGICAL PROPERTIES	DRY / COND		
Molding shrinkage (parallel)	0.35 / *	%	ISO 294-4
Molding shrinkage (normal)	1.2 / *	%	ISO 294-4
MECHANICAL PROPERTIES	DRY / COND		
Tensile modulus	11500 / 12000	MPa	ISO 527-1/-2
Tensile modulus (120°C)	8000 / -	MPa	ISO 527-1/-2
Tensile modulus (160°C)	5000	MPa	ISO 527-1/-2
Stress at break	150 / 140	MPa	ISO 527-1/-2
Stress at break (120°C)	95 / –	MPa	ISO 527-1/-2
Stress at break (160°C)	65	MPa	ISO 527-1/-2
Strain at break	2/1.9	%	ISO 527-1/-2
Strain at break (120°C)	2.5 / -	%	ISO 527-1/-2
Strain at break (160°C)	3.6	%	ISO 527-1/-2
Flexural modulus	11000 / 11500	MPa	ISO 178
Flexural strength	240 / 220	MPa	ISO 178
Charpy impact strength (+23°C)	47 / 47	kJ/m²	ISO 179/1eU
Charpy notched impact strength (+23°C)	7/7	kJ/m²	ISO 179/1eA
THERMAL PROPERTIES	DRY / COND		
Melting temperature (10°C/min)	325 / *	°C	ISO 11357-1/-3
Temp. of deflection under load (1.80 MPa)	305 / *	°C	ISO 75-1/-2

Seller represents and warrants exclusively that on the date of delivery by Seller the product shall be in conformity with the specifications agreed upon. Seller makes no other representations or

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Property Data

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PROPERTIES	TYPICAL DATA	UNIT	TEST METHOD
Coeff. of linear therm. expansion (parallel)	0.2 / *	E-4/°C	ISO 11359-1/-2
Coeff. of linear therm. expansion (normal)	0.6 / *	E-4/°C	ISO 11359-1/-2
Coeff. of linear therm. expansion (parallel)	0.3	E-4/°C	ASTM D696
Coeff. of linear therm. expansion (normal)	0.35	E-4/°C	ASTM D696
Burning Behav. at 1.5 mm nom. thickn.	V-0 / *	class	IEC 60695-11-10
Thickness tested	1.5 / *	mm	IEC 60695-11-10
UL recognition	Yes / *	_	
Burning Behav. at 3.0 mm nom. thickn.	V-0 / *	class	IEC 60695-11-10
Thickness tested	V-0 / *	mm	IEC 60695-11-10
UL recognition	3/*	-	_
Relative Temperature Index – electrical	130	°C	UL746B
RTI electrical (Thickness (1) tested)	0.75	mm	UL746B
ELECTRICAL PROPERTIES	DRY / COND		
Volume resistivity	>1E13 / >1E13	Ohm*m	IEC 62631-3-1
Electric strength	33 / 33	kV/mm	IEC 60243-1
Comparative tracking index	600 / -	V	IEC 60112
Relative permittivity (100Hz)	4.2 / 4.2	_	IEC 62631-2-1
Relative permittivity (1 MHz)	3.9 / 3.9		IEC 62631-2-1
Relative permittivity (1GHz)	3.8 / 3.9	_	IEC 61189-2-721
OTHER PROPERTIES	DRY / COND		
Humidity absorption	1.6 / *	%	Sim. to ISO 62
Density	1460 / -	kg/m³	ISO 1183

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Seller is not responsible or liable for the design of the products of the Customer and it is the responsibility of the Customer to determine that the Seller's product is safe, complies with application laws and regulations, and is technically or otherwise fit for its intended use. Seller does not endorse or claim suitability of its products for a specific application and disclaims each and every representation or warranty, whether express or implied, in that respect.

Typical values are indicative only and are not to be construed as being binding specifications. Colorants in the product or other additives may cause significant variations in typical values.

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